

2017 IEEE Optical Interconnects Conference (OI 2017)

**Santa Fe, New Mexico, USA
5-7 June 2017**



**IEEE Catalog Number: CFP17HSD-POD
ISBN: 978-1-5090-5017-8**

**Copyright © 2017 by the Institute of Electrical and Electronics Engineers, Inc
All Rights Reserved**

Copyright and Reprint Permissions: Abstracting is permitted with credit to the source. Libraries are permitted to photocopy beyond the limit of U.S. copyright law for private use of patrons those articles in this volume that carry a code at the bottom of the first page, provided the per-copy fee indicated in the code is paid through Copyright Clearance Center, 222 Rosewood Drive, Danvers, MA 01923.

For other copying, reprint or republication permission, write to IEEE Copyrights Manager, IEEE Service Center, 445 Hoes Lane, Piscataway, NJ 08854. All rights reserved.

****** This is a print representation of what appears in the IEEE Digital Library. Some format issues inherent in the e-media version may also appear in this print version.***

IEEE Catalog Number:	CFP17HSD-POD
ISBN (Print-On-Demand):	978-1-5090-5017-8
ISBN (Online):	978-1-5090-5016-1

Additional Copies of This Publication Are Available From:

Curran Associates, Inc
57 Morehouse Lane
Red Hook, NY 12571 USA
Phone: (845) 758-0400
Fax: (845) 758-2633
E-mail: curran@proceedings.com
Web: www.proceedings.com

CURRAN ASSOCIATES INC.
proceedings
.com



Optical Interconnects Conference 2017

5-7 June 2017
Hilton Santa Fe Historic Plaza
Santa Fe, New Mexico USA

MaA - Welcome & Plenary I 8:30am-9:45am - Mesa Ballroom Welcome & Plenary I

MaA1: Silicon Photonics and the Future of Optical Connectivity in the Data Center (Page 1)
Thomas Liljeborg (*Intel Corporation*)

MB - Silicon Photonics 10:15am-11:45am - Mesa Ballroom

MB1: Use of 3D Technology for Silicon Photonics (Page N/A)
Sylvie Menezo (*CEA-LETI*)

MB2: Intermodulation Crosstalk of Graphene-Enabled Electro-Optic Microring Modulators for DWDM Interconnects (Page 3)

Nathan C. Abrams (*Columbia University*)
Meisam Bahadori (*Columbia University*)
Christopher T. Phare (*Columbia University*)
Michal Lipson (*Columbia University*)
Keren Bergman (*Columbia University*)

MB3: A Two-Segment Optical daC 40 Gb/s PaM4 Silicon Microring Resonator Modulator Transmitter in 65nm CMOs (Page 5)

Ashkan Roshan-Zamir (*Texas A&M University*)
Binhao Wang (*Texas A&M University*)
Shashank Telaprolu (*Texas A&M University*)
Kunzhi Yu (*Texas A&M University*)
Cheng Li (*Hewlett-Packard Enterprise*)
M. Ashkan Seyedi (*Hewlett-Packard Enterprise*)
Marco Fiorentino (*Hewlett-Packard Enterprise*)
Raymond Beausoleil (*Hewlett-Packard Enterprise*)
Samuel Palermo (*Texas A&M University*)

MB4: Comparison of DAC-less PAM4 Modulation in Segmented Ring Resonator and Dual Cascaded Ring Resonator (Page 7)

Anthony H. K. Park (*University of British Columbia*)
Ajith S. Ramani (*University of British Columbia*)
Lukas Chrostowski (*University of British Columbia*)
Sudip Shekhar (*University of British Columbia*)

MB5: 29-GHz Small-signal Modulation Bandwidth for Directly Current-modulated 980-nm Oxide-aperture VCSELs (Page 9)

Ricardo Rosales (*Technische Universität Berlin*)
Philip Moser (*Stanford University*)
James A. Lott (*Technische Universität Berlin*)

MC - Advance Devices 1:15pm-3:15pm - Mesa Ballroom

MC1: Photonic Integration in Commercial Manufacturing Lines (Page N/A)
Ajey Jacob (*Sandia National Laboratories*)

MC2: Characterization of Systematic Process Variation in a Silicon Photonic Platform (Page 11)

Nicholas Boynton (*Sandia National Laboratories and University of New Mexico*)
Andrew Pomerene (*Sandia National Laboratories*)
Andrew Starbuck (*Sandia National Laboratories*)
Anthony Lentine (*Sandia National Laboratories*)
Christopher T. DeRose (*Sandia National Laboratories*)

MC3: Scalable and Broadband Silicon Photonics Chip to Fiber Optical Interface Using Polymer Waveguides (Page 13)

Antonio La Porta (*IBM Research - Zurich*)
Roger Dangel (*IBM Research - Zurich*)
Daniel Jubin (*IBM Research - Zurich*)
Norbert Meier (*IBM Research - Zurich*)
Folkert Horst (*IBM Research - Zurich*)
Bert Jan Offrein (*IBM Research - Zurich*)

MC4: Substrate Removal for Ultra Efficient Silicon Heater-Modulators (Page 15)

Nicholas J. D. Martinez (*Sandia National Laboratories*)
Christopher T. DeRose (*Sandia National Laboratories*)
Robert Jarecki (*Sandia National Laboratories*)
Andrew L. Starbuck (*Sandia National Laboratories*)
Andrew T. Pomerene (*Sandia National Laboratories*)
Douglas C. Trotter (*Sandia National Laboratories*)
Anthony L. Lentine (*Sandia National Laboratories*)

MC5: The Benefit of Mid-board Optic and Other Flyover Technology (Page 17)

Fred Copping (*Samtec Inc.*)
David Langsam (*Samtec Inc.*)
Adam Page (*Samtec Inc.*)
Marc Verdiell (*Samtec Inc.*)

MC6: Hybrid Optical Engines for On-board Optical Applications (Page N/A)

Bardia Pezeshki (*Kaia Corp*)

TuAa - Plenary II 8:30am-9:45am - Mesa Ballroom

TuAa1: Attojoule Optoelectronics - Saving More Energy with Optics (Page 19)

David A. B. Miller (*Stanford University*)

TuAa2: Programmable Optical Power Distribution in Silicon Photonic Platform (Page 21)

Alexander Gazman (*Columbia University*)
Meisam Bahadori (*Columbia University*)
Ziyi Zhu (*Columbia University*)
Keren Bergman (*Columbia University*)

TuAa3: Integrated Fresnel Zone Plate in the SOI Backend for Improved Laser to Chip Coupling Efficiency (Page 23)

M. Henniges (*Sicoya GmbH and Technische Universität Berlin*)
S. Meister (*Sicoya GmbH*)
H. Rhee (*Sicoya GmbH*)
C. Theiss (*Sicoya GmbH*)
H. Robers (*Technische Universität Berlin*)
M. Grehn (*Sicoya GmbH*)
D. Stolarek (*IHP*)
L. Zimmermann (*IHP*)
U. Woggon (*Technische Universität Berlin*)

TuB - Next Generation Data Centers 10:15am-11:45am - Mesa Ballroom

TuB1: Roadmap to Optical I/O (Page N/A)

Brad Booth (*Microsoft*)

TuB2: Application Regime and Distortion Metric for Multivariate RF Photonics (Page 25)

A. N. Tait (*Princeton University*)
T. Ferreira de Lima (*Princeton University*)
M. P. Chang (*Princeton University*)
M. A. Nahmias (*Princeton University*)
B. J. Shastri (*Princeton University*)
P. R. Prucnal (*Princeton University*)

TuB3: Flexible On-chip Frequency Comb Generation Using a SOI Dual-drive MZM (Page 27)

Jiachuan Lin (*Université Laval*)
Hassan Sepehrian (*Université Laval*)
Leslie A. Rusch (*Université Laval*)
Wei Shi (*Université Laval*)

TuB4: Microprocessor with Photonics I/O (Page N/A)

Chen Sun (*Ayer Lab*)

TuC - High Speed Communication I 1:15pm-3:15pm - Mesa Ballroom

TuC1: DSP Solutions for Next Generation Intra and Inter-data Center Connectivity (Page N/A)

Sudeep Bhoja (*Inphi*)

TuC2: Real-Time 100 Gb/s NRZ-OOK Transmission with a Silicon Photonics GeSi Electro-Absorption Modulator (Page 29)

J. Verbist (*Ghent University - IMEC*)
M. Verplaetse (*Ghent University - IMEC*)
S. A. Srinivasan (*Ghent University - IMEC and IMEC*)
P. De Heyn (*IMEC*)
T. De Keulenaer (*Ghent University - IMEC*)
R. Vaernewyck (*Ghent University - IMEC*)
R. Pierco (*Ghent University - IMEC*)
A. Vyncke (*Ghent University - IMEC*)
P. Verheyen (*IMEC*)
S. Balakrishnan (*IMEC*)
G. Leplage (*IMEC*)
M. Pantouvaki (*IMEC*)
P. Absil (*IMEC*)
X. Yin (*Ghent University - IMEC*)
G. Roelkens (*Ghent University - IMEC*)
G. Torfs (*Ghent University - IMEC*)

J. Van Campenhout (*IMEC*)
J. Bauwelinck (*Ghent University - IMEC*)

TuC3: 56 Gb/s Direct Modulation of an InP-on-Si DFB Laser Diode (Page 31)

A. Abbasi (*Ghent University - IMEC*)
B. Moeneclaey (*Ghent University - IMEC*)
J. Verbist (*Ghent University - IMEC*)
X. Yin (*Ghent University - IMEC*)
J. Bauwelinck (*Ghent University - IMEC*)
G. Roelkens (*Ghent University - IMEC*)
G. Morthier (*Ghent University - IMEC*)

TuC4: Towards Efficient 100 Gb/s Serial Rate Optical Interconnects: a Duobinary Way (Page 33)

X. Yin (*Ghent University - IMEC*)
M. Verplaetse (*Ghent University - IMEC*)
L. Breyné (*Ghent University - IMEC*)
J. Van Kerrebrouck (*Ghent University - IMEC*)
T. De Keulenaer (*Ghent University - IMEC*)
A. Vyncke (*Ghent University - IMEC*)
R. Pierco (*Ghent University - IMEC*)
R. Værnewyck (*Ghent University - IMEC*)
S. Spiga (*TUM*)
M.-C. Amann (*TUM*)
J. Chen (*KTH*)
G. Van Steenberge (*Ghent University - IMEC*)
G. Torfs (*Ghent University - IMEC*)
J. Bauwelinck (*Ghent University - IMEC*)

TuC5: 100G Transition: Electrical & Optical, Challenges & Opportunities (Page 35)

Francesco Caggioni (*MACOM*)

WAa - Energy Efficiency 8:30am-9:45am - Mesa Ballroom

WAa1: Datacenter Optical Interconnects: Requirements and Challenges (Page 37)

Chongjin Xie (*Alibaba Group*)

WAa2: Scalability of Microring-Based Crossbar for All-to-All Optical Interconnects (Page 39)

Xian Xiao (*University of California, Davis*)
Roberto Proietti (*University of California, Davis*)
S. J. Ben Yoo (*University of California, Davis*)

WAa3: Highly Scalable, Low-Crosstalk Architecture for Ring-Based Optical Space Switch Fabrics (Page 41)

Qixiang Cheng (*Columbia University*)
Meisam Bahadori (*Columbia University*)
Sébastien Rumley (*Columbia University*)
Keren Bergman (*Columbia University*)

WAa4: Accelerated Out-of-Band Arbitration of a Microring-Based Silicon Photonic System (Page 43)

David M. Calhoun (*Columbia University*)
Erik F. Anderson (*Columbia University*)
M. H. N. Hattink (*Columbia University*)
Sébastien Rumley (*Columbia University*)
Keren Bergman (*Columbia University*)

WB - High Speed Communication II 10:15am-11:45am - Mesa Ballroom

WB1: Silicon Photonics for Nx56G NRZ Optical Interconnects (Page N/A)

Joris Van Campenhout (*IMEC*)

WB2: A 48-Gb/s Software Defined Optical Transceiver Using Multi-tone PAM/CAP Modulation (Page 45)

Fan Yang (*Shanghai Jiao Tong University*)
Wenjia Zhang (*Shanghai Jiao Tong University*)
Zuyuan He (*Shanghai Jiao Tong University*)

WB3: Machine Learning of SVM Classification Utilizing Complete Binary Tree Structure for PAM-4/8 Optical Interconnection (Page 47)

Guoyao Chen (*Shanghai Jiao Tong University*)
Lin Sun (*Shanghai Jiao Tong University*)
Ke Xu (*Harbin Institute of Technology*)
Jiangbing Du (*Shanghai Jiao Tong University*)
Zuyuan He (*Shanghai Jiao Tong University*)

WB4: High-Capacity PAM4 and DMT for Short Reach Interconnects (Page N/A)

Jeffrey Lee

WC - VCSEL and Advance Communication 1:15pm-3:00pm - Mesa Ballroom

WC1: VCSEL Based SWDM Links for Data Centers (Page 49)

Chris Kocot (*Finisar Corp.*)
Anna Tatarczak (*Finisar Corp.*)
Jim A. Tatum (*Finisar Corp.*)

WC2: 30 Gbit/s 1.7 pJ/bit Common-Cathode Tunable 850-nm-VCSEL Driver in 28 nm Digital CMOS (Page 51)

Laszlo Szilagyi (*Technische Universität Dresden*)
Guido Belfiore (*Technische Universität Dresden*)

Ronny Henker (*Technische Universität Dresden*)
Frank Ellinger (*Technische Universität Dresden*)

WC3: VCSeL Modulation Capacity: Continued Improvements or Physical Limits? (Page 53)

A. Larsson (*Chalmers University of Technology*)
J. S. Gustavsson (*Chalmers University of Technology*)
E. Haglund (*Chalmers University of Technology*)
E. P. Haglund (*Chalmers University of Technology*)
T. Lengyel (*Chalmers University of Technology*)
E. Simpanen (*Chalmers University of Technology*)
M. Jahed (*Chalmers University of Technology*)

WC4: High Capacity SWDM PAM4 Transmissions over NG-WBMMF at Extended Reach (Page 55)

Y. Sun (*OFS Fitel, LLC*)
F. Chang (*Inphi Corp.*)
K. Scott (*OFS Fitel, LLC*)
R. Lingle Jr. (*OFS Fitel, LLC*)
T. Gray (*Finisar Corp.*)
J. Tatum (*Finisar corp.*)
S. Bhjoa (*Inphi Corp.*)

WC5: Proposal of Isolator-free Optical Interconnect Using Low-noise Graded-index Plastic Optical Fiber for Pluggable 4K/8K Optical Interface (Page 57)

Azusa Inoue (*Keio University*)
Yasuhiro Koike (*Keio University*)